



PATENT

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Applicant(s): Ligang Zhang, et al.

Title: REDISTRIBUTION LAYER SHIELDING OF A CIRCUIT ELEMENT

Application No.: 10/814,816

Filed:

March 31, 2004

Examiner: Jennifer E. Matisiak

Group Art Unit:

2811

Atty. Docket No.: 026-0041

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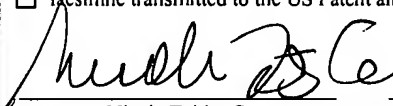
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- ☐ This Information Disclosure Statement is filed within three months of the filing date of a national application other than a continued prosecution application under § 1.53(d) or within three months of entry of the national stage as set forth in § 1.491 in an international application. Therefore, no fee is required.
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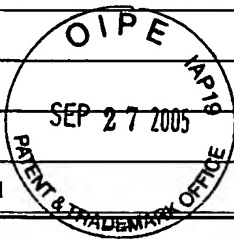


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PTO/SB/08B (Substitute for form 1449/PTO)		Attorney Docket No.: 026-0041
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		Filing Date: March 31, 2004
		Group Art Unit: 2811
		Examiner Name: Jennifer E. Matisiak
Sheet 1 of 1		Date Submitted: September 23, 2005



### NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No. <sup>1</sup>	Include name of author (in CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
	AA	FROMMBERGER, Michael, et al., "Integration of Crossed Anisotropy Magnetic Core Into Toroidal Thin-Film Inductors," IEEE Transactions on Microwave Theory and Techniques, Vol. 53, No. 6, June 2005, pp. 2096-2100.	
	AB	KIM, Sung-Jin, et al., "Realization of High-Q Inductors Using Wirebonding Technology," School of Electronics Engineering, Ajou University, AP-ASIG Proceedings, August 1999, 4 pages.	
	AC	LONG, John R. and Miles A. Copeland, "The Modeling, Characterization, and Design of Monolithic Inductors for Silicon RF IC's," IEEE Journal of Solid-State Circuits, Vol. 32, No. 3, March 1997, pp. 357-369.	
	AD	SOH, H. T., et al., "Through-Wafer Vias (TWV) and their Applications in 3 Dimensional Structures," Proceedings of 1998 International Conference on Solid State Devices and Materials, September 1998, 12 pages.	
	AE	TANG, Chih-Chun, et al., "Miniature 3-D Inductors in Standard CMOS Process," IEEE Journal of Solid-State Circuits, Vol. 37, No. 4, April 2002, pp. 471-480.	
	AF	TRELEAVEN, Dave and Dick James, "Integrated Circuit Passive Components," Whitepapers, Chipworks, <a href="http://www.chipworks.com/resources/resources_whitepapers.asp">www.chipworks.com/resources/resources_whitepapers.asp</a> , 4 pages.	
	AG	TSUI, Hau-Yiu and Jack Lau, 2003 IEEE MTT-S Digest, pp. 225-228.	
	AH	WU, Joyce H., et al., "A Through-Wafer Interconnect in Silicon for RFICs," IEEE Transactions on Electron Devices, Vol. 51, No. 11, November 2004, pp. 1765-1771.	
	AI	ZANNOTH, Markus, et al., "A Fully Integrated VCO at 2 GHz," IEEE Journal of Solid-State Circuits, Vol. 33, No. 12, December 1998, pp. 1987-1991.	
	AJ	ZOU, Jun, et al., "Development of Vertical Planar Coil Inductors Using Plastic Deformation Magnetic Assembly (PDMA), 2001 IEEE International Microwave Symposium, May 2001, 4 pages.	
Examiner Signature		Date Considered	

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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